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- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the D input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the D input may be changed without affecting the levels at the outputs.

The SN54' family is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN74' family is characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE

	INPUT	S		OUTP	UTS
PRE	CLR	CLK	D	α	ā
L	Н	×	Х	Н	L
н	L	×	Х	L	H.
Ł	L	X	Х	нt	H
н	Н	Ť	Н	н	L
н	н	t	L	L	Н
н	Н	L	Х	Q ₀ .	\overline{a}_0

[†] The output levels in this configuration are not guaranteed to meet the minimum levels in V_{OH} if the lows at preset and clear are near V_{IL} maximum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

logic symbol[‡]



[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5474...J PACKAGE
SN54LS74A, SN54S74...J OR W PACKAGE
SN7474...N PACKAGE
SN74LS74A, SN74S74...D OR N PACKAGE
(TOP VIEW)



SN5474 . . . W PACKAGE (TOP VIEW)



SN54LS74A, SN54S74 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram (positive logic)



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schematics of inputs and outputs

74



'S74



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schematic

'LS74A



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Input voltage: '74, 'S74		5.5 V
'LS74A		7 V
Operating free-air temperature range: SN54'.		-55°C to 125°C
SN74'.	• • • • • • • • • • • • • • • • • • • •	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



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recommended operating conditions

				SN547	4		SN7474		UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			8.0	V
ЮН	High-level output current			-	- 0.4			- 0.4	mA
10L	Low-level output current				16			16	mA
		CLK high	30			30			
tw	Pulse duration	CLK low	37			37			ns
**		PRE or CLR low	30			30			
t _{su}	Input setup time before CLK†		20			20			ns
th	Input hold time-data after CLK †		5			5			ns
TA	Operating free-air temperature		- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		_		- ot	:	SN5474			SN7474		UNIT
PA	RAMETER	1	EST CONDITIO	NS	MIN	TYP\$	MAX	MIN	TYP#	MAX	UNI
VIK		VCC = MIN,	t ₁ = - 12 mA				- 1.5			1.5	٧
Vон		V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,	2.4	3.4		2.4	3.4		٧
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,		0.2	0.4		0.2	0.4	V
11		VCC = MAX,	V ₁ = 5.5 V				1			1	mA
	D						40			40	
ίн	ČLR	1	V = 2.4.V				120			120	μΑ
***	All Other	V _{CC} = MAX,	V ₁ = 2.4 V				80			80	l
	D						- 1.6			- 1.6	
	PRE §	1					- 1.6			- 1.6	mA
IIL	CLR §	VCC = MAX,	V ₁ = 0.4 V		1		- 3.2			- 3.2] ""
	CLK	1					- 3.2			- 3.2]
los1		V _{CC} = MAX			- 20		– 57	- 18		- 57	mA
I _{CC} #		V _{CC} = MAX,	See Note 2			8.5	15		8.5	15	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching charateristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				15	25		MHz
[†] PLH		-				25	ns
	PRE or CLR	Q or \overline{Q}	$R_L = 400 \Omega$, $C_L = 15 pF$			40	ns
tPHL					14	25	ns
tPLH t	CLK	Q or Q			20	40	ns
tPHL]	i						

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡]All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§]Clear is tested with preset high and preset is tested with clear high.

Not more than one output should be shown at a time.

[#]Average per flip-flop.

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recommended operating conditions

			St	154LS7	4A		SN74LS	74A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Уcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			8.0	V
ЮН	High-level output current				- 0.4			- 0.4	mA
loL	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		25	MHz
		CLK high	25			25			ns
t _W	Pulse duration	PRE or CLR low	25			25			113
		High-level data	20			20			ns
t _{su}	Setup time-before CLK†	Low-level data	20			20			113
th	Hold time-data after CLK †		5			5			ns
TA	Operating free-air temperature		- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					S	N54LS7	4A	SI	UNIT		
PA	RAMETER	TES	T CONDITIONS [†]		MIN	TYP‡	MAX	MIN	TYP‡	MAX	ONT
VIK		V _{CC} = MIN,	I _I = — 18 mA				1.5			- 1.5	V
V _{OH}		V _{CC} = MIN, I _{OH} = 0.4 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		>
		V _{CC} = MIN, I _{OL} = 4 mA	VIL = MAX,	V _{IH} = 2 V,		0.25 0			0.25	0.4	V
VOL		V _{CC} = MIN, I _{OL} = 8 mA	$V_{IL} = MAX$, $V_{IH} = 2 V$,					0.35		0.5	
	D or CLK	14 14 14	\/ - 7\/				0.1			0.1	mA
ΙĮ	CLR or PRE	$V_{CC} = MAX$,	V ₁ = 7 V				0.2			0.2	1117 (
	D or CLK						20			20	μΑ
ЧН	CLR or PRE	V _{CC} = MAX,	$V_{\parallel} = 2.7 \text{ V}$				40			40	<u> </u>
	D or CLK						- 0.4			- 0.4	mA
IIL	CLR or PRE	V _{CC} = MAX,	V _I = 0.4 V				- 0.8			- 0.8	1111/2
los§	•	V _{CC} = MAX,	See Note 4		- 20		100	- 20		- 100	mA
ICC (To	ital)	V _{CC} = MAX,	See Note 2			4	8		4	8	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
fmax					25	33		MHz
tPLH		Q or $\overline{\mathbf{Q}}$	$R_L = 2 k\Omega$,	C լ = 15 pF		13	25	ns
tPHL	CLR, PRE or CLK	Q or Q				25	40	ns

Note 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with $V_0 = 2.25$ V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

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recommended operating conditions

				SN54S7	14		SN74S7	4	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage		2			2			٧
VIL	Low-level input voltage				0.8			8.0	٧
ЮН	High-level output current				- 1			– 1	mA
IOL	Low-level output current				20			20	mA
		CLK high	6			6			
tw	Pulse duration	CLK low	7.3			7.3			ns
•		CLR or PRE low	7			7			<u> </u>
		High-level data	3			3			ns
t _{su}	Setup time, before CLK f	Low-level data	3			3			1113
th	Input hold time - data after CLK †		2			2			ns
TA	Operating free-air temperature		- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				-+		SN54S74	1		SN74S7	4	UNIT
PAF	RAMETER		TEST CONDITION	Si	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
VIK		V _{CC} = MIN,	I _I = - 18 mA,				- 1.2			- 1.2	٧
Voн		V _{CC} = MIN, 1 _{OH} = -1 mA	V _{IH} = 2 V, V	1L = 0.8 V,	2.5	3.4		2.7	3.4		٧
VOL	·	V _{CC} = MIN, I _{OL} = 20 mA	V _{1H} = 2 V, V	/IL = 0.8 V,			0.5			0.5	٧
1 ₁		V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
	D						50			50	
lін	CLR	V _{CC} = MAX,	V ₁ = 2.7 V				150			150	μА
	PRE or CLK		•				100			100	
	D						– 2			- 2	
	CLR¶						- 6			- 6	mA
կլ	PRE¶	V _{CC} = MAX,	V ₁ = 0.5 V				4			-4	""
	CLK						- 4			– 4	
loss		V _{CC} = MAX			- 40		- 100	- 40		- 100	mA
ICC#		V _{CC} = MAX,	See Note 2			15	25		15	25	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is

switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
fmax				75	110		MHz
^t PLH	PRÉ or CLR	Q or Q			4	6	ns
	PRE or CLR (CLK high)	a or a	$R_1 = 280 \Omega$. $C_1 = 15 pF$		9	13.5	ns
^t PHL	PRE or CLR (CLK low)	u or u	R _L = 280 Ω, C _L = 15 pF		5	8	
^t PLH		_			6	9	ns
tPHL t	CLK	Q or Q			6	9	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25 ^{\circ}\text{C}$.

Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

¹Clear is tested with preset high and preset is tested with clear high.

[#]Average per flip-flop.

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07101BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07101BCA	Samples
JM38510/07101BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07101BDA	Samples
JM38510/07101BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07101BDA	Samples
JM38510/30102B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102B2A	Samples
JM38510/30102B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102B2A	Samples
JM38510/30102BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BCA	Samples
JM38510/30102BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BCA	Samples
JM38510/30102BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BDA	Samples
JM38510/30102BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BDA	Samples
JM38510/30102SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S CA	Samples
JM38510/30102SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S CA	Samples
JM38510/30102SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S DA	Samples
JM38510/30102SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S DA	Samples
M38510/07101BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07101BCA	Samples
M38510/07101BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07101BCA	Samples
M38510/07101BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07101BDA	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
M38510/07101BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07101BDA	Samples
M38510/30102B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102B2A	Samples
M38510/30102B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102B2A	Samples
M38510/30102BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BCA	Samples
M38510/30102BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BCA	Samples
M38510/30102BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BDA	Samples
M38510/30102BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30102BDA	Samples
M38510/30102SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S CA	Sample
M38510/30102SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S CA	Sample
M38510/30102SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S DA	Sample
M38510/30102SDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/30102S DA	Sample
SN54LS74AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS74AJ	Sample
SN54LS74AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS74AJ	Sample
SN54S74J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S74J	Sample
SN54S74J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S74J	Sample
SN74LS74AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LS74A	
SN74LS74AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LS74A	
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	Sample
SN74LS74ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	Sample





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	Samples
SN74LS74ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	Samples
SN74LS74ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	Samples
SN74LS74ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS74A	Samples
SN74LS74AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS74AN	Samples
SN74LS74AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS74AN	Samples
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS74AN	Samples
SN74LS74ANE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS74AN	Samples
SN74LS74ANSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS74A	Samples
SN74LS74ANSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS74A	Samples
SN74LS74ANSRG4	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS74A	Samples
SN74LS74ANSRG4	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS74A	Samples
SN74S74D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S74	Samples
SN74S74D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S74	Samples
SN74S74N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S74N	Samples
SN74S74N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S74N	Samples
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 74AFK	Samples
SNJ54LS74AFK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 74AFK	Samples
SNJ54LS74AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS74AJ	Samples
SNJ54LS74AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS74AJ	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS74AW	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS74AW	Samples
SNJ54LS74AW	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS74AW	Samples
SNJ54S74J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S74J	Samples
SNJ54S74J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S74J	Samples
SNJ54S74W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S74W	Samples
SNJ54S74W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S74W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

www.ti.com 13-Feb-2025

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OTHER QUALIFIED VERSIONS OF SN54LS74A, SN54LS74A-SP, SN54S74, SN74LS74A, SN74S74:

Catalog: SN74LS74A, SN54LS74A, SN74S74

Military: SN54LS74A, SN54S74

• Space : SN54LS74A-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com 7-Dec-2024

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS74ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS74ANSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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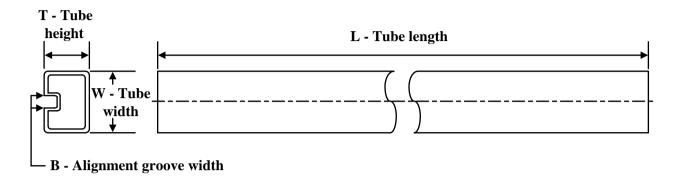
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS74ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LS74ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS74ANSR	SOP	NS	14	2000	367.0	367.0	38.0



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07101BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/30102B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30102BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/30102SDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/07101BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30102B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/30102BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30102SDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS74AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS74AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS74ANE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS74ANE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74S74D	D	SOIC	14	50	506.6	8	3940	4.32
SN74S74N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S74N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS74AFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS74AW	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54S74W	W	CFP	14	25	506.98	26.16	6220	NA

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



INSTRUMENTS www.ti.com

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-150.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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